

# FFPF30UA60S

## Ultrafast II Diode 30 A, 600 V



ON Semiconductor®

[www.onsemi.com](http://www.onsemi.com)

### Description

The FFPF30UA60S is a ultrafast II diode with low forward voltage drop. This device is intended for use as freewheeling and clamping diodes in a variety of switching power supplies and other power switching applications. It is specially suited for use in switching power supplies and industrial application.

### Features

- Ultrafast Recovery,  $t_{RR} = 90 \text{ ns}$  (@  $I_F = 30 \text{ A}$ )
- Max Forward Voltage,  $V_F = 2.2 \text{ V}$  (@  $T_C = 25^\circ\text{C}$ )
- 600 V Reverse Voltage and High Reliability
- Avalanche Energy Rated
- This Device is Pb-Free and is RoHS Compliant

### Applications

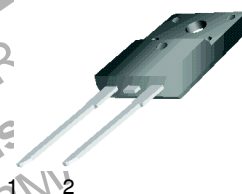
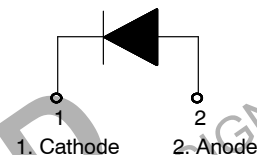
- Boost Diode in PFC and SMPS
- Welder, UPS and Motor Control Application

### ABSOLUTE MAXIMUM RATINGS

$T_C = 25^\circ\text{C}$  unless otherwise noted

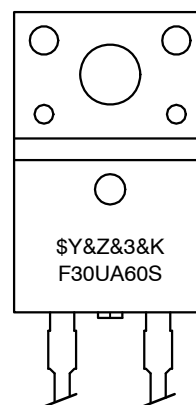
Symbol	Parameter	Rating	Unit
$V_{RRM}$	Peak Repetitive Reverse Voltage	600	V
$V_{RWM}$	Working Peak Reverse Voltage	600	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 43^\circ\text{C}$	30	A
$I_{FSM}$	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	180	A
$T_J, T_{STG}$	Operating Junction and Storage Temperature	- 65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



TO-220, 2-Lead  
CASE 221AS

### MARKING DIAGRAM



\$Y = ON Semiconductor Logo  
&Z&3 = Data Code (Year & Week)  
&K = Lot  
F30UA60S = Specific Device Code

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# FFPF30UA60S

## THERMAL CHARACTERISTICS $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max.	Unit
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	2.5	$^\circ\text{C/W}$

## PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFPF30UA60S	F30UA60S	TO-220F-2L	Tube	N/A	N/A	50

## ELECTRICAL CHARACTERISTICS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_F$ (Note 1)	$I_F = 30\text{ A}$ $I_F = 30\text{ A}$	$T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	— —	2.2 2.0	V
$I_R$ (Note 1)	$V_R = 600\text{ V}$ $V_R = 600\text{ V}$	$T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	— —	100 150	$\mu\text{A}$
$t_{RR}$ $I_{RR}$ $Q_{RR}$	$I_F = 30\text{ A}$ , $di_F/dt = 200\text{ A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	— — —	90 8 360	ns A nC
$W_{AVL}$	Avalanche Energy ( $L = 40\text{ mH}$ )	20	—	—	mJ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse: Test Pulse Width = 300  $\mu\text{s}$ , Duty Cycle = 2%

## Test Circuit and Waveforms

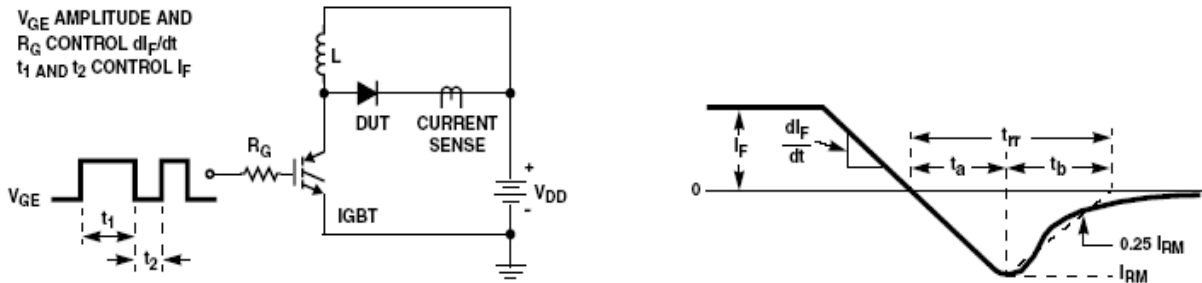


Figure 1. Diode Reverse Recovery Test Circuit & Waveform

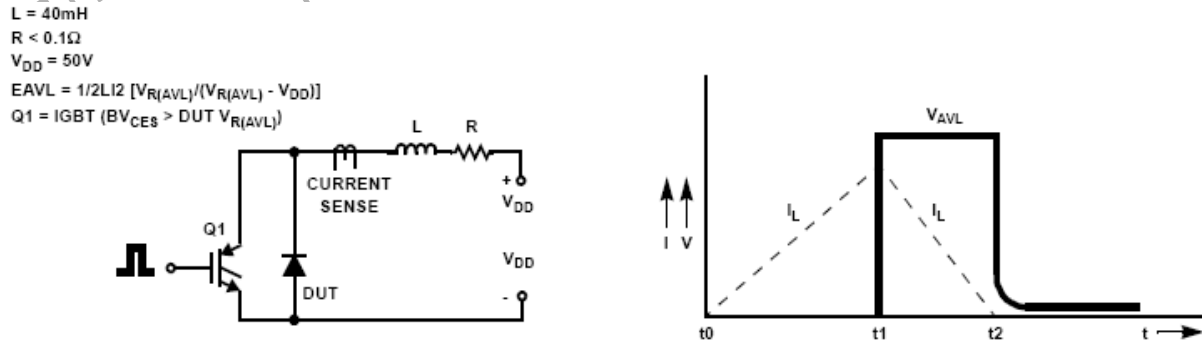


Figure 2. Unclamped Inductive Switching Test Circuit & Waveform

## TYPICAL PERFORMANCE CHARACTERISTICS

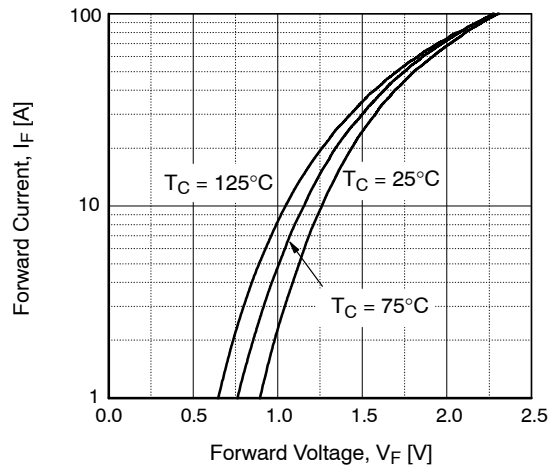


Figure 3. Typical Forward Voltage Drop vs. Forward Current

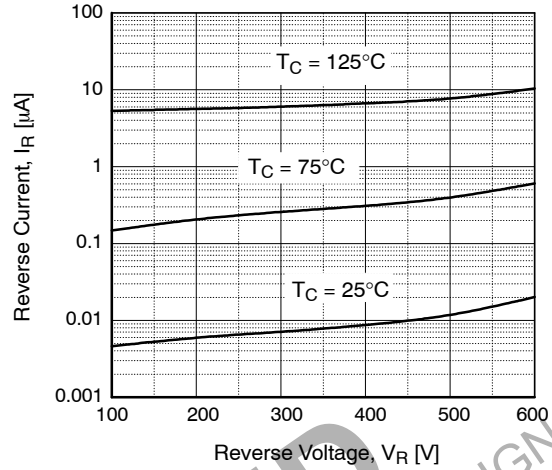


Figure 4. Typical Reverse Current vs. Reverse Voltage

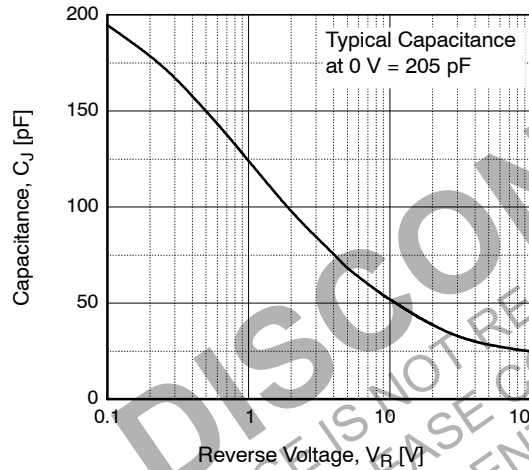


Figure 5. Typical Junction Capacitance

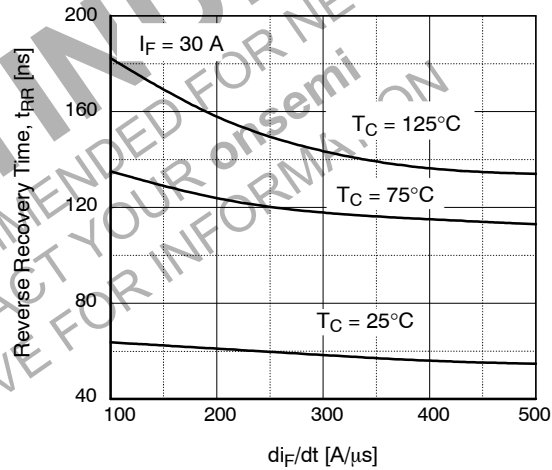
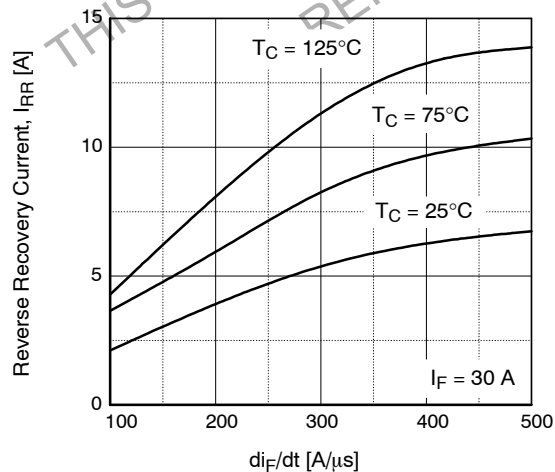
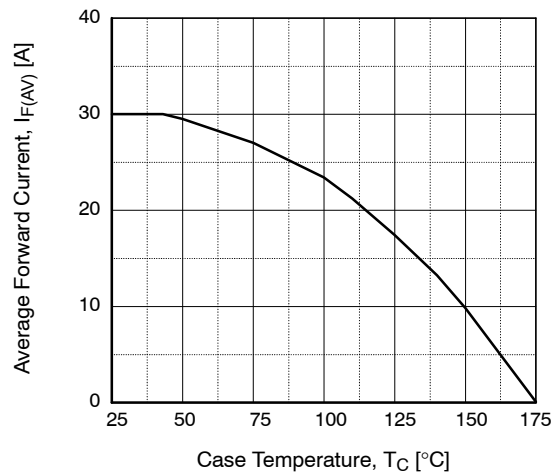
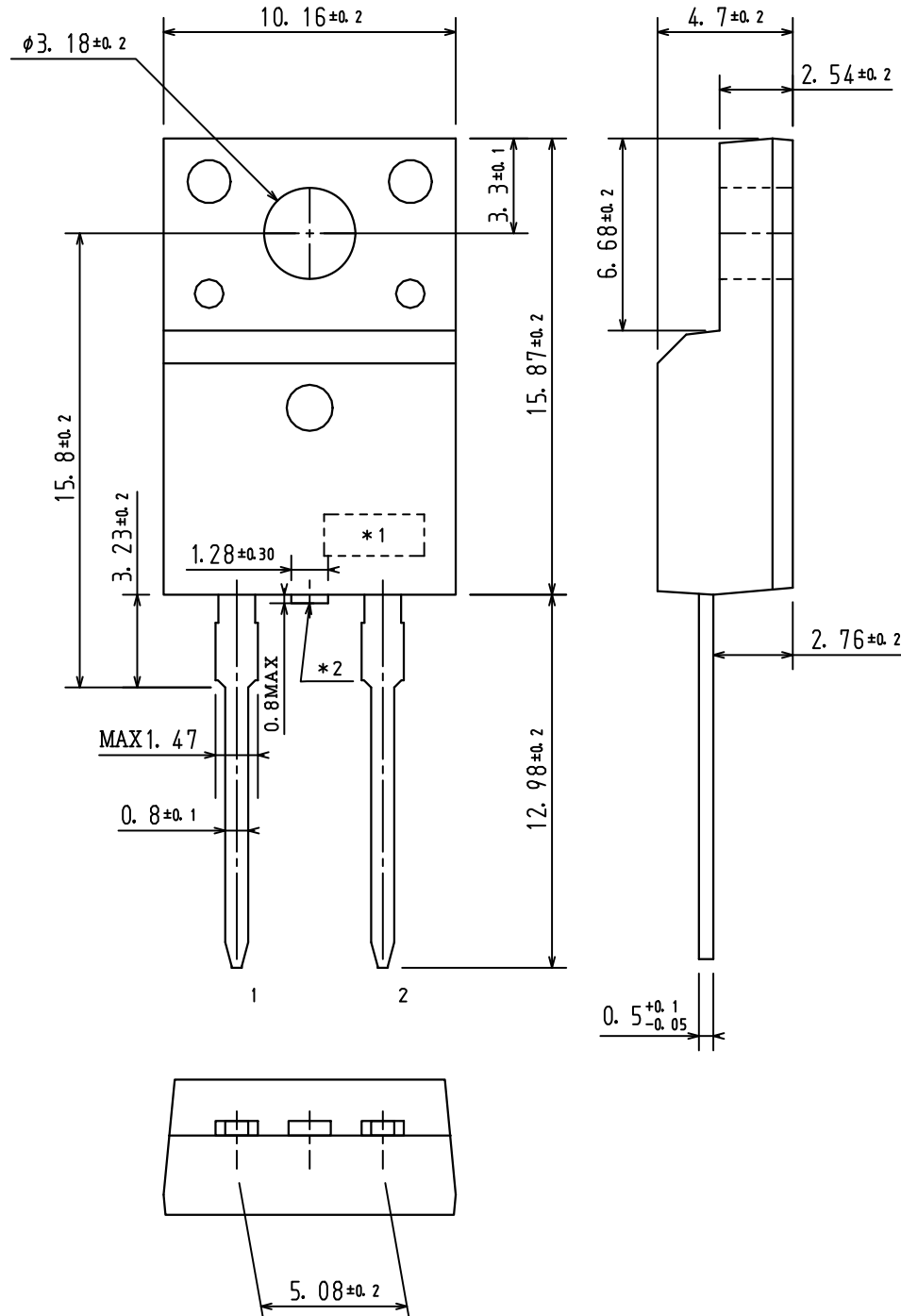
Figure 6. Typical Reverse Recovery Time vs.  $di_F/dt$ Figure 7. Typical Reverse Recovery Current vs.  $di_F/dt$ 

Figure 8. Forward Current Derating Curve

**TO-220 Fullpack, 2-Lead / TO-220F-2FS**  
CASE 221AS  
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